

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2.0x1.25 mm INFRARED EMITTING DIODE

Part Number: APT2012SF4C-PRV

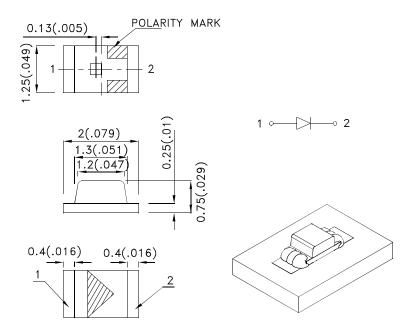
Features

- 2.0mmx1.25mm SMT LED,0.75mm thickness.
- Mechanically and spectrally matched to the phototransistor.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAJ1371 **REV NO: V.3B DATE: DEC/18/2011** PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1203008893 DRAWN: C.H.HAN

Selection Guide

Part No.	Dice	Lens Type	Po (mW/sr) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
APT2012SF4C-PRV	SF4 (GaAlAs)	Water Clear	0.8	1.5	120°

Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Radiant intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Тур.	Max.	Units	Test Conditions	
Forward Voltage [1]	SF4	VF	1.3	1.6	V	IF=20mA	
Reverse Current	SF4	lR		10	uA	V _R = 5V	
Capacitance	SF4	С	90		pF	VF=0V;f=1MHz	
Peak Spectral Wavelength	SF4	λP	880		nm	IF=20mA	
Spectral Bandwidth	SF4	Δλ1/2	50		nm	I==20mA	

Note:

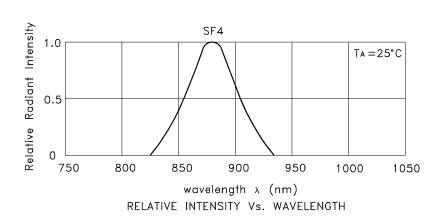
- Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

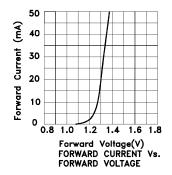
Aboolato maximam ratingo at 171 20 0						
Parameter	Symbol	SF4	Units			
Power dissipation	PD	80	mW			
DC Forward Current	lF	50	mA			
Peak Forward Current [1]	İFS	1.2	Α			
Reverse Voltage	VR	5	V			
Operating Temperature	Та	-40 To +85	°C			
Storage Temperature	Тѕтс	-40 To +85	°C			

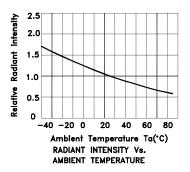
Note: 1. 1/100 Duty Cycle, 10µs Pulse Width.

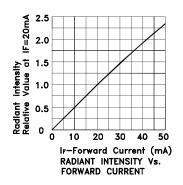
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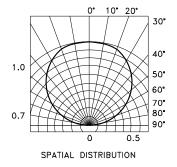


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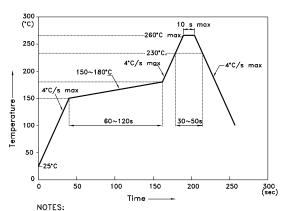
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

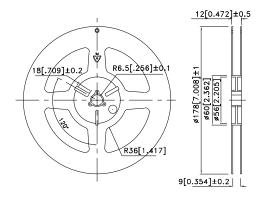
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

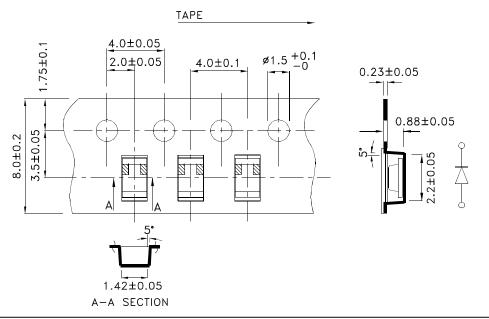
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units: mm)

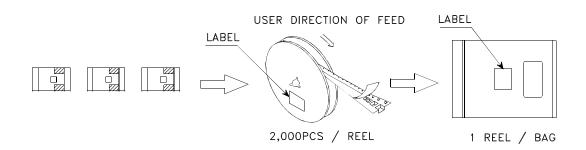


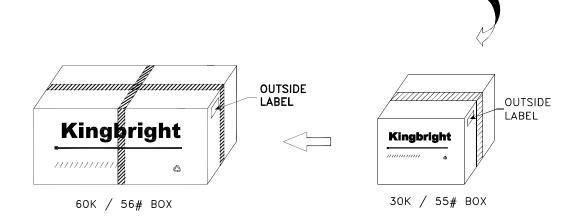
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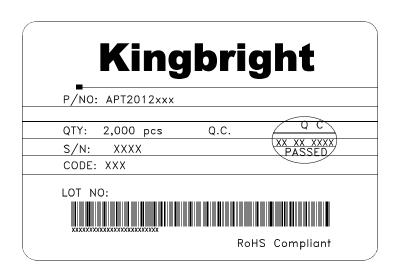
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PACKING & LABEL SPECIFICATIONS

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